T-1 (3mm) SOLID STATE LAMP

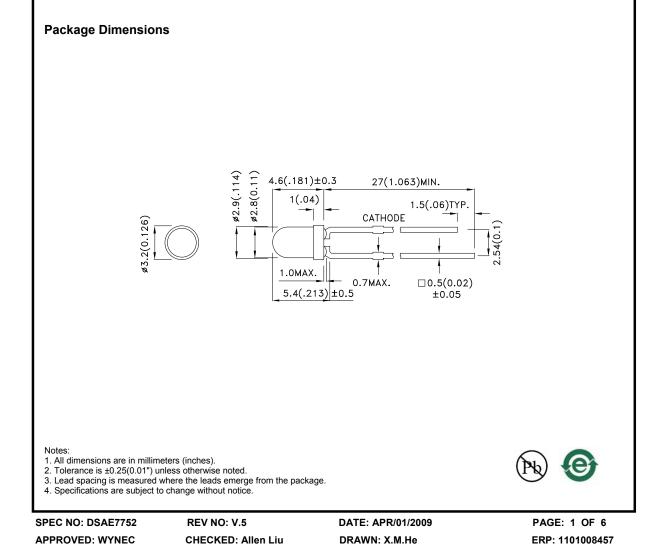
Part Number: WP7104SYC Super Bright Yellow

Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- RoHS compliant.

Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.



Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP7104SYC	Super Bright Yellow (AlGaInP)	WATER CLEAR	280	700	34°

Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	28		nm	I⊧=20mA
С	Capacitance	Super Bright Yellow	25		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Yellow		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

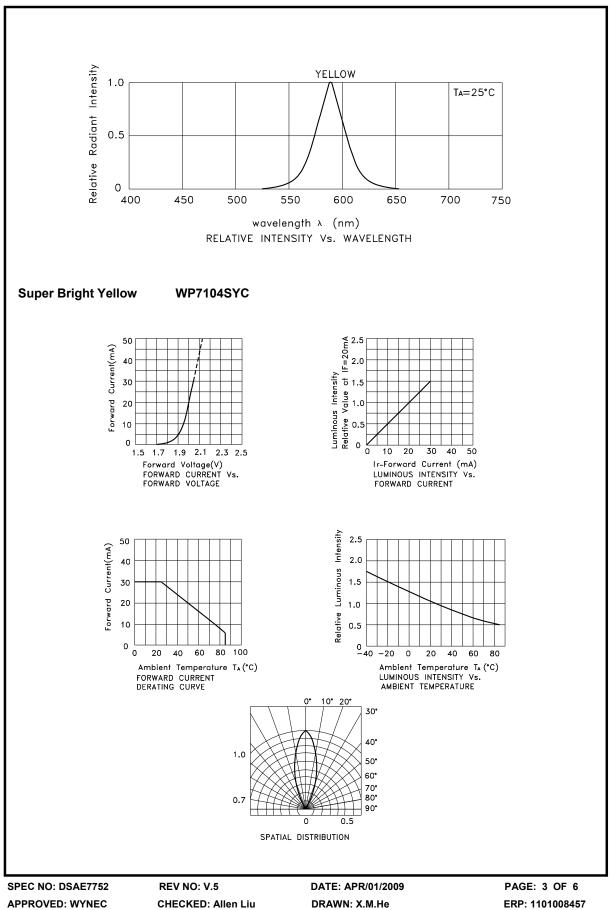
Parameter	Super Bright Yellow		
Power dissipation	75	mW	
DC Forward Current	30		
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base.			

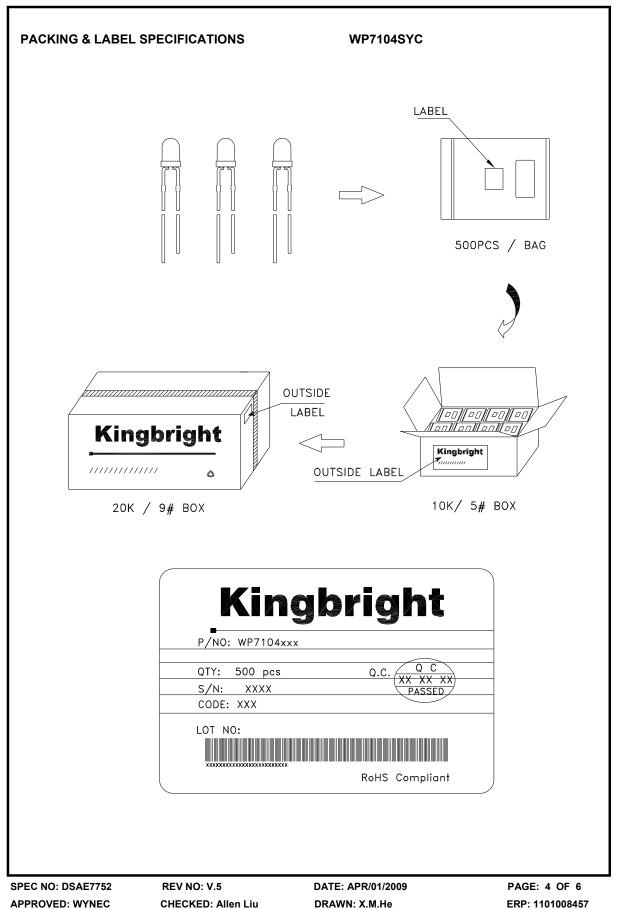
3. 5mm below package base.

SPEC NO: DSAE7752 APPROVED: WYNEC

REV NO: V.5 CHECKED: Allen Liu DATE: APR/01/2009 DRAWN: X.M.He

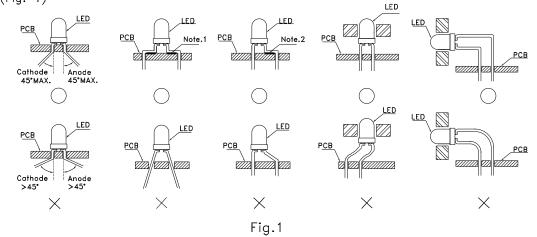
PAGE: 2 OF 6 ERP: 1101008457





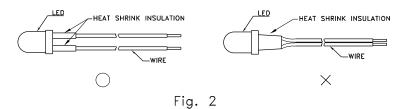
LED MOUNTING METHOD

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.
(Fig. 1)



" \bigcirc " Correct mounting method " \times " Incorrect mounting method Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

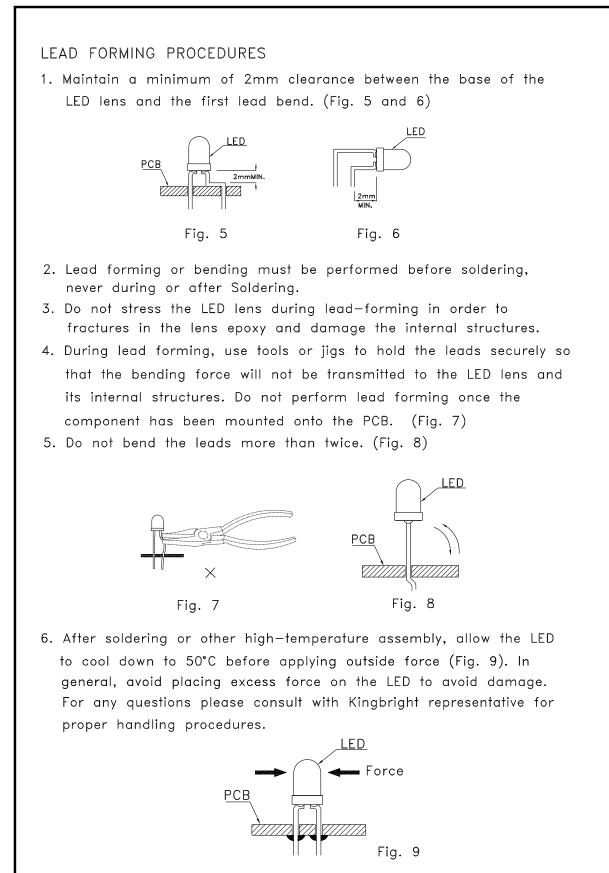
2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig. 2)



3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

PCB STAND-OFF F Fig. 3 Fig. 4

SPEC NO: DSAE7752 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: APR/01/2009 DRAWN: X.M.He PAGE: 5 OF 6 ERP: 1101008457



SPEC NO: DSAE7752 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: APR/01/2009 DRAWN: X.M.He PAGE: 6 OF 6 ERP: 1101008457